

## PATENT ABSTRACTS OF JAPAN

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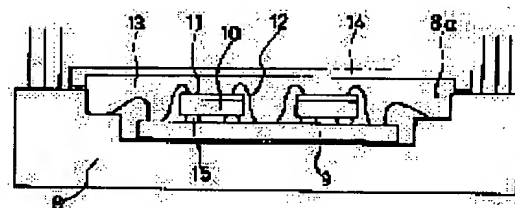
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## (54) SEMICONDUCTOR DEVICE

## (57)Abstract:

PURPOSE: To improve radiation without requiring a radiating resin, a radiating material, and its sealing step for a multi-chip module using face-down bonding.

CONSTITUTION: A metallic layer 11 is mounted on the rear face of an IC chip 10, which is mounted on a base board 9 in a face-down bonding step, and the metallic layer 11 and the base board 9 are connected with a radiating bonding wire 12 to improve radiating characteristics.



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